ACCOUNT ON ACCUMENTATION	© Cop	terial Compo pyright 2005. IPC, Bannock ternational and Pan-Americ	kburn, Illinois	All rights reserve	tion with lower	level p	oarts, the	declaration	n encor	npasses all lov	wer level mat	erials for which	if the item is an assembly the the manufacturer has nis declaration.		
		Web Site for Informati		rd	Form Type * Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Inform							
Supplier Information															
Company Name * Company Unique				Unique ID Au	Response Date *				Response Do	cument ID					
SEMTECH CORPORATIO					2012-05-09										
Contact Name *	Title - Contact		Phone - Con	Email - Contact *				D Francis	- O	A 4 la	I Danis and the				
ROYA READER		Quality Assurance Co	ustomer S	(805) 389-2742			rreader@semtech.com			Duplicat	e Contact	-> Autnorized	d Representative		
Authorized Representati	ve *	Title - Representative	)	Phone - Representative *			Email - Representative *			Supplier Com	ments or UR	_ for Addition	al Information		
ROYA READER	Quality Assurance C	ustomer S	<b>€</b> 805) 389-27	rreader@semtech.com											
Requester Item Number		Mfr Item Number		Mfr Item Name	Effective Date Ve		Version	Manufa	cturing Site	Weight *	UOM	Unit Type			
	EZ1117CM-			0.8A, 3.3V Pc	9			Malaysia		1,388.25	mg	Each			
Alternate Recommendation						Alternate Item C			mments						
Manufacturing Proces	s Inf	formation													
Terminal Plating / Grid Array Material Terminal B			ase Alloy	ting Peak Process Body Temp			Temper	erature Max Time at Peak Temperatur			ber of Reflow Cycles				
Matte Tin (Sn)			CU Alloy	py 1			260 (				<b>30</b> se	econds 3			
Comments		-			1										

Save the fields in this form to a file Export Data Import fields from a file into this form	Inches of Date	all of the on this form Reset Form	Lock the fields on this form to prevent changes	Lock Supplier Fields								
RoHS Material Composition Declaration Decl												
RoHS Directive 2002/95/EC RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information informa												
Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version EL-2006/690/EC												
+ - 7a. Lead in high melting temperature type solders (i.e. lead based solder alloys con-	taining 85% by weight or more lead	).										
Declaration Signature												
Instructions: Complete all of the required fields on all pages of this fo	rm. Select the "Accepted"	on the Supplier Acceptance drop-d	lown. This will display the sign	nature area. Digitally sign								

the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## **Homogeneous Material Composition Declaration for Electronic Products**

**Subltem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem		Homogeneous	Weight	Unit of		Lo	vel	Substance Category			Substance	CAS	Evennt	Weight	Unit of Measure	Tolerance		PPM
	Name		Material	weight	Measure		Le	vei	Substance Category			Substance	CAS	Exempl	weight		-	+	FFIVI
+1 -1	SILICON CHIP	+M -M	Silicon Die	3.781	mg	+C -C	Sup	pplier		+S	-S	Silicon (Si)	7440-21-3		3.781	mg			2,724
+1 -1	LEAD FRAME, TO2	+M -M	HCI-12S	828.071	lmg	+C -(	Sup	pplier		+S	-S	Copper (Cu)	7440-50-8		827.035	mg			373,15
									+S	-S	Tin (Sn)	7440-31-5		1.0361	mg			467	
		+M -M	Silver plating	0.8289	mg	+C -0	Sup	pplier		+S	-S	Silver (Ag)	7440-22-4		0.8289	mg			374
+1 -1	DIE ATTACHED MA	+M -M	PbSn5 Solder wi	1.5	mg	+C -(	A		Lead/Lead Compound	+S	-S	Lead	7439-92-1	7a. Lead	1.425	mg			643
+C -C Supplier								+S	-S	Tin (Sn)	7440-31-5		0.075	mg			34		
+1 -1	BONDING WIRE	+M -M	Gold Wire	1	mg	+C -(	Sup	pplier		+S	-S	Gold (Au)	7440-57-5		1	mg			451
+1 -1	MOLDING COMPOL	+M -M	CEL9220HF13	543.97	mg	+C -(	Sup	pplier		+S	-S	Epoxy Resins	Proprietary		38.0779	mg			17,181
										+S	-S	Phenol Resin	Proprietary		24.4787	mg			11,045
										+S	-S	Silica Fused	60676-86-0		445.5114	mg			201,01
										+S	-S	Carbon Black	1333-86-4		0.544	mg			245
										+S	-s	Metal Hydroxide	Proprietary		27.1985	mg			12,272
										+S	-s	Others			8.1596	mg			3,682
+1 -1	FINISH PLATING	+M -M	Tin alloy	9.1	mg	+C -0	Sup	pplier		+S	-S	Tin (Sn)	7440-31-5		9.1	mg			4,106